

## DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

### "Method for Bonding Wafers to Produce Stacked Integrated Circuits"

the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, Section 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and so identified, and I have also identified below any foreign application for patent or inventor's certificate on this invention filed by me or my legal representatives or assigns and having a filing date before that of the application on which priority is claimed.

<u>Number</u>	<u>Country</u>	<u>Day/Month/Year Filed</u>	<u>Priority Claimed - Yes or No</u>
none			

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

<u>Application Serial No.</u>	<u>Filing Date</u>	<u>Status</u>
none		

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these

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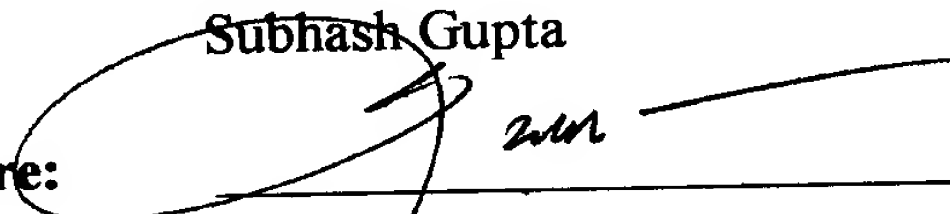
statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint Calvin B. Ward (Reg. No. 30,896), with full power of substitution and revocation, to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith and request that all correspondence and telephone calls in respect to this application be directed to The Law Offices of Calvin B. Ward, 18 Crow Canyon Court, Suite 305, San Ramon, CA 94583, Telephone No. (925) 855-0413.

**Full name of first inventor:**

Subhash Gupta

**Inventor's signature:**



**Date:** 4.16.2001

**Residence and Post Office Address:**

5 Tot Heights  
Singapore 507806

**Citizenship:**

U.S.

**Full name of second inventor:**

Paul Kwok Keung Ho

**Inventor's signature:**



**Date:** 16-APR-2001

**Residence and Post Office Address:**

BLK217, Bishan St. 23, #16-315  
Singapore 570217


**Citizenship:**

Chinese

**Full name of third inventor:**

Sangki Hong

**Inventor's signature:**



**Date:** 16/04/2001

**Residence and Post Office Address:**

11 Upper Bukit Timar View, #05-03, Bukit Regency  
Singapore 588137

**Citizenship:**

Korean

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